

**LISTING OF THE CLAIMS**

1. (Original) A system comprising:  
an integrated circuit on a VLSI die; and  
an embedded micro-controller constructed on the VLSI die, the micro-controller adapted to monitor and control the VLSI environment to optimize the integrated circuit operation.
2. (Original) The system of claim 1 wherein the embedded micro-controller monitors one or more of the parameters selected from the group consisting of:  
temperatures at one or more locations on the integrated circuit;  
the power supplied to the integrated circuit;  
the operating clock frequency of the integrated circuit;  
the power supply voltage; and  
the power supply current supplied to the integrated circuit.
3. (Original) The system of claim 1 wherein the embedded micro-controller controls at least one of the following parameters:  
temperatures at one or more locations on the integrated circuit;  
the integrated circuit power supply;  
the operating clock frequency of the integrated circuit;  
the power supply voltage; and  
the power supply current supplied to the integrated circuit.
4. (Original) The system of claim 1 wherein the integrated circuit comprises two or more processor cores, each core having a integer unit and a floating point unit, the micro-controller further comprising:  
temperature sensors at each of the integer units and floating point units on each of the cores.
5. (Original) The system of claim 1 further comprising:  
embedded ammeters constructed on the VLSI integrated circuit die, the ammeters comprising voltage controlled oscillators.

6. (Original) The system of claim 1 further comprising:  
fuses that provide hardware selection of VLSI integrated circuit environment parameters that are monitored by the embedded micro-controller.
7. (Original) The system of claim 1 further comprising:  
firmware for controlling operations of the embedded micro-controller.
8. (Original) A method for monitoring and controlling an integrated circuit comprising:  
providing an embedded micro-controller on a same VLSI die as the integrated circuit;  
and  
monitoring and controlling a VLSI environment of the integrated circuit with the embedded micro-controller.
9. (Original) The method of claim 8 further comprising:  
monitoring, by the embedded micro-controller, one or more integrated circuit parameters selected from the group consisting of:  
temperatures at one or more locations on the integrated circuit;  
the power supplied to the integrated circuit;  
the operating clock frequency of the integrated circuit;  
the power supply voltage; and  
the power supply current supplied to the integrated circuit.
10. (Original) The method of claim 8 further comprising:  
controlling, by the embedded micro-controller, one or more processor parameters selected from the group consisting of:  
temperatures at one or more locations on the integrated circuit;  
the integrated circuit power supply;  
the operating clock frequency of the integrated circuit;  
the power supply voltage; and  
the power supply current supplied to the integrated circuit.

11. (Original) The method of claim 8 further comprising:  
controlling, using the embedded micro-controller, the VLSI environment to optimize  
an integrated circuit operating power level to approach a design limit.

12. (Original) The method of claim 8 further comprising:  
monitoring, using the embedded micro-controller, a temperature in a location of the  
integrated circuit; and  
reducing, using the embedded micro-controller, a power supply voltage in response to  
an over-temperature condition in the location.

13. (Original) The method of claim 8 further comprising:  
monitoring, using the embedded micro-controller, a temperature in a location of the  
integrated circuit; and  
reducing, using the embedded micro-controller, a processor operating clock frequency  
in response to an over-temperature condition in the integrated circuit.

14. (Original) The method of claim 8 wherein the integrated circuit is a processor,  
the method further comprising:  
monitoring, using the embedded micro-controller, a temperature in a first core of the  
processor; and  
transferring, using the embedded micro-controller, a processing workload from the  
first core to a second core of the processor.

15. (Original) The method of claim 8 further comprising:  
monitoring, using the embedded micro-controller, current levels in the integrated  
circuit using ammeters comprising one or more voltage controlled oscillators.

16. (Original) A computer program product comprising a computer usable medium having computer readable program code embedded therein, the computer readable program code comprising:

code for controlling an embedded micro-controller constructed on a VLSI integrated circuit die with a processor, wherein the micro-controller monitors and controls a VLSI environment of the processor.

17. (Original) The computer program product of claim 16 further comprising: code for monitoring, by the embedded micro-controller, one or more integrated circuit parameters selected from the group consisting of:

- temperatures at one or more location on the integrated circuit;
- the power supplied to the integrated circuit;
- the operating clock frequency of the integrated circuit;
- the power supply voltage; and
- the power supply current supplied to the integrated circuit.

18. (Original) The computer program product of claim 16 further comprising: code for controlling, by the embedded micro-controller, one or more integrated circuit parameters selected from the group consisting of:

- temperatures at one or more locations on the integrated circuit;
- the integrated circuit power supply;
- the operating clock frequency of the integrated circuit;
- the power supply voltage; and
- the power supply current supplied to the integrated circuit.

19. (Original) The computer program product of claim 16 further comprising: code for controlling the VLSI environment to optimize an integrated circuit operating power level to approach a design limit.

20. (Original) The computer program product of claim 16 further comprising:  
code for monitoring a temperature in a core of the processor; and  
code for reducing a power supply voltage in response to an over-temperature  
condition in the core.

21. (Original) The computer program product of claim 16 further comprising:  
code for monitoring a temperature in a core of the processor; and  
code for reducing a processor operating frequency in response to an over-temperature  
condition in the core.

22. (Original) The computer program product of claim 16 further comprising:  
code for monitoring a temperature in a first core of the processor; and  
code for transferring a processing workload from the first core to a second core of the  
processor.

23. (Original) The computer program product of claim 16 further comprising:  
code for monitoring current levels in the integrated circuits using ammeters  
comprising one or more voltage controlled oscillators.

24. (Original) A system for monitoring and controlling an integrated circuit  
comprising:  
means for providing an embedded micro-controller on a same VLSI die as the  
integrated circuit; and  
means for monitoring and controlling a VLSI environment of the integrated circuit  
with the embedded micro-controller.

25. (Original) The system of claim 24 further comprising:  
means for controlling, using the embedded micro-controller, the VLSI environment to  
optimize an integrated circuit operating power level to approach a design limit.

26. (Original) The system of claim 24 further comprising:  
means for monitoring, using the embedded micro-controller, a temperature in a location of the integrated circuit; and  
means for reducing, using the embedded micro-controller, a power supply voltage in response to an over-temperature condition in the location.

27. (Original) The system of claim 24 further comprising:  
means for monitoring, using the embedded micro-controller, a temperature in a location of the integrated circuit; and  
means for reducing, using the embedded micro-controller, a processor operating clock frequency in response to an over-temperature condition in the integrated circuit.

28. (Original) The system of claim 24 wherein the integrated circuit is a processor, the method further comprising:  
means for monitoring, using the embedded micro-controller, a temperature in a first core of the processor; and  
means for transferring, using the embedded micro-controller, a processing workload from the first core to a second core of the processor.